



# On-shore Advanced Packaging Capabilities GOMACTech-2024

18 March 2024

TIME (EDT)	TOPICS
1300 to 1310	Onshoring Workshop Overview
1310 to 1330	RESHAPE Overview
<b>Funded Onshoring Capabilities by RESHAPE/ Title III</b>	
1330 to 1350	Bridg/ Skywater (Si Interposer standup; IMEC license transfer to the Bridg/Skywater facility)
1350 to 1410	Neocity (fan out wafer level packaging standup; DECA license transfer to the Bridg/Skywater facility)
1410 to 1430	Micros (300mm wafer prep/bumping standup)
1430-1450	Calumet (HDBU/HDI standup)
1450 to 1510	GreenSource (HDBU/HDI standup)
1510-1530	Break
1530-1630	Panel of 5 performers, tri-service RESHAPE team, NGMS, BAE